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AMENDMENTS TO THE SPECIFICATION

Please replace Table 2 on page 13 with the following amended Table 2:

Table 2

Table 2						
	Anionic surfact	ant Amount (ppm)	Sulfate ion (ppm)	Methanol (% by mass)	Chloride ion (ppm)	Dimensional controllability
Example 13	C ₁₂ H ₂₅ -(O)-0-(Q) SO ₃ NH ₄ SO ₃ NH ₄	3000	500	0.005	2000	В
Example 14	$C_{12}H_{25}$ - \bigcirc -0- \bigcirc \bigcirc \bigcirc SO ₃ NH ₄	3000	700	0.005	2000	В
Example 15	C12H25- O-O-O SO3NH4 SO3NH4	3000	5000	0.005	2000	В
Example 16	C ₁₂ H ₂₅ -O-O-G SO ₃ NH ₄ SO ₃ NH ₄	3000	700	0.05	2000	В
Example 17	C ₁₂ H ₂₅ -O-O-Q SO ₃ NH ₄ SO ₃ NH ₄	3000	700	0.3	2000	В
Example 18	C ₁₂ H ₂₅	3000	700	2.5	2000	В
Example 19	C5H11-(O)-0-(O)-SO3NH4	1000	700	0.3	300	Α
Example 20	C5H11-(O)-0-(O)-SO3NH4	1000	700	0.3	500	В
Example 21	C5H11-(O)-O-(O)-SO3NH4	1000	700	0.005	300	В
Example 22	C5H11-(O)-0-(O)-\$03NH4	1000	700	0.005	500	В
Example 23	C12H25-(O)-0-(Q) SO3NH4 SO3NH4	20000	700	0.3	300	Α
Example 24	C ₁₂ H ₂₅ -O-O-Q SO ₃ NH ₄ SO ₃ NH ₄	50000	700	0.3	300	В
Example 22 25	C ₁₂ H ₂₅ -(O)-0-(Q) SO ₃ NH ₄ SO ₃ NH ₄	3000	700	0.3	300	В
						

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AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A developer composition for resists, comprising an organic quaternary ammonium base as a main component, said organic quaternary ammonium base having a lower alkyl group or a lower hydroxyalkyl group, wherein the lower alkyl group or lower hydroxyalkyl group has 1 to 5 carbon atoms, wherein said organic quaternary ammonium base is present in an amount from 0.1 to 10% by mass;

said developer further comprising an anionic surfactant in an amount from 500 1,000 to 100,000 50,000 ppm represented by the following general formula (I):

$$R_1$$
 R_2
 R_3
 R_4
 R_5

wherein at least one of R₁ and R₂ represents an alkyl or alkoxy group having 5 to 18 15 carbon atoms and the other one represents a hydrogen atom, or an alkyl or alkoxy group having 5 to 18 15 carbon atoms, and at least one of R₃, R₄ and R₅ represents an ammonium sulfonate group or a sulfonic acid-substituted ammonium group and the others represent a hydrogen atom, an ammonium sulfonate group or a sulfonic acid-substituted ammonium group;

 SO_4^{2-} in an amount from 10 50 to 10,000 5,000 ppm; and a lower alcohol in an amount from 0.05 0.005 to 2.5% by mass.

- 2. (Canceled)
- 3. (Canceled)
- 4. (Previously presented) A method for formation of a resist pattern, comprising applying a resist composition on a substrate to form a resist layer, prebaking the resist layer, selectively exposing the prebaked resist layer to light, and alkali-developing the exposed resist layer with the developer composition for resists according to claim 1 to form a resist pattern.
- 5. (**Previously presented**) The developer composition for resists according to claim 1, wherein said lower alcohol has 1 to 5 carbon atoms.
- 6. (**Previously presented**) The developer composition for resists according to claim 5, wherein the lower alcohol is ethanol or methanol.

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7. (**Previously presented**) The developer composition for resists according to claim 1, wherein the amount of said organic quaternary ammonium base is 0.1 to 10% by mass based on the developer composition for resists.

- 8. (**Currently amended**) The developer composition for resists according to claim 1, further comprising a halogen ion in an amount of 1,000 ppm or less 300 to 2,000 ppm.
- 9. (**Previously presented**) The developer composition for resists according to claim 8, wherein the amount of the halogen ion is from 300 to 1,000 ppm.
- 10. (New) The developer composition for resists according to claim 1, wherein said organic quaternary ammonium base is in an amount from 2 to 5% by mass.
- 11. (New) The developer composition for resists according to claim 1, wherein said SO_4^{2-} is in an amount from 100 to 1,000 ppm.
- 12. (New) The developer composition for resists according to claim 1, wherein said lower alcohol in is in an amount from 0.1 to 1% by mass.
- 13. (New) The developer composition for resists according to claim 8, wherein said halogen ion is in an amount of 1,000 ppm or less.